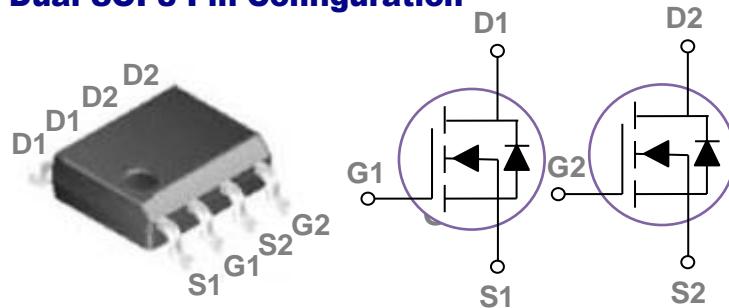


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### Dual SOP8 Pin Configuration



BVDSS	RDS(ON)	ID
30V	20mΩ	7.5A

### Features

- 30V, 7.5A, RDS(ON) = 20mΩ @ VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2<sup>nd</sup> SR

### Absolute Maximum Ratings T<sub>c</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>Gs</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>c</sub> =25°C)	7.5	A
	Drain Current – Continuous (T <sub>c</sub> =100°C)	4.8	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	30	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	14	mJ
I <sub>AS</sub>	Single Pulse Avalanche Current <sup>2</sup>	17	A
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25°C)	2.1	W
	Power Dissipation – Derate above 25°C	0.017	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	60	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.04	---	$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>3</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=6\text{A}$	---	15	20	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=3\text{A}$	---	23	30	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	1.2	1.5	2.5	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	-4	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_D=6\text{A}$	---	13	---	S

**Dynamic and switching Characteristics**

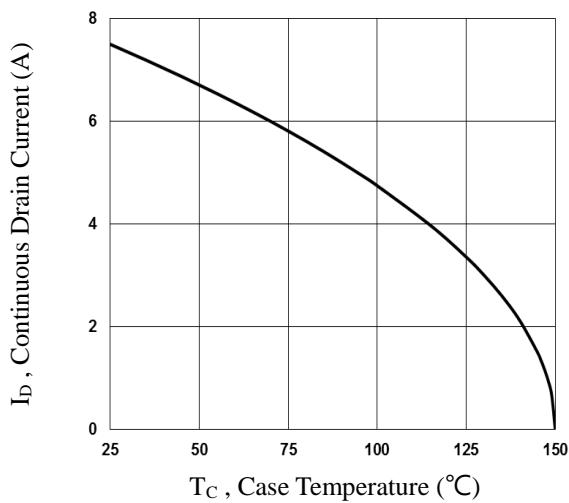
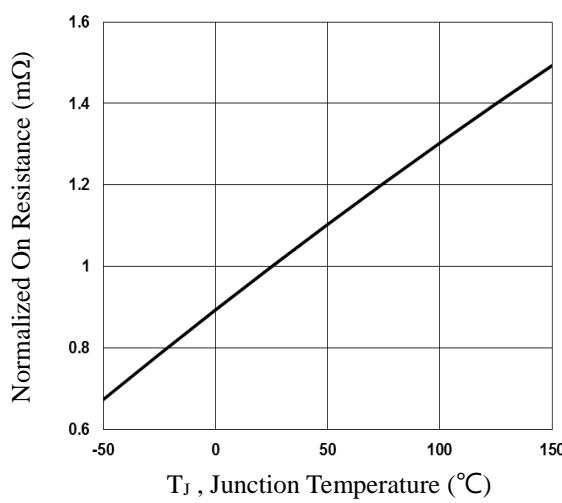
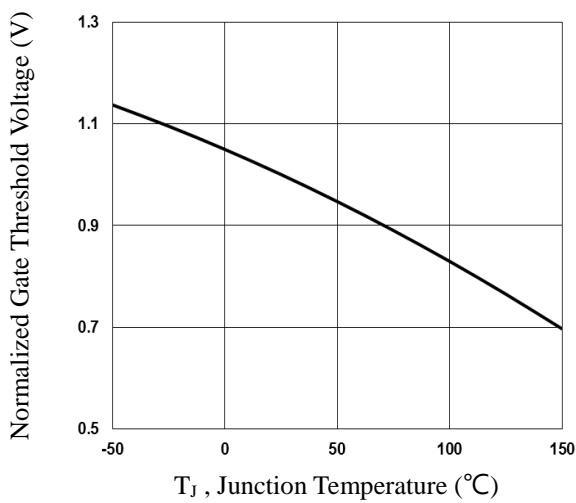
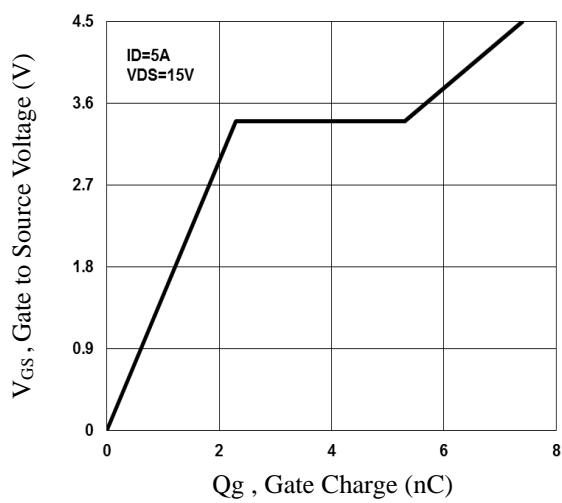
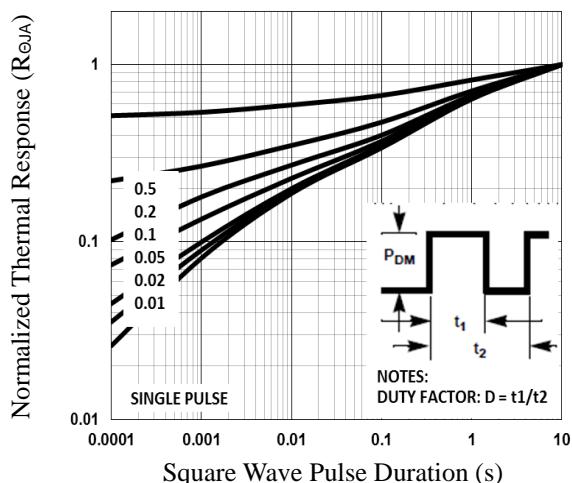
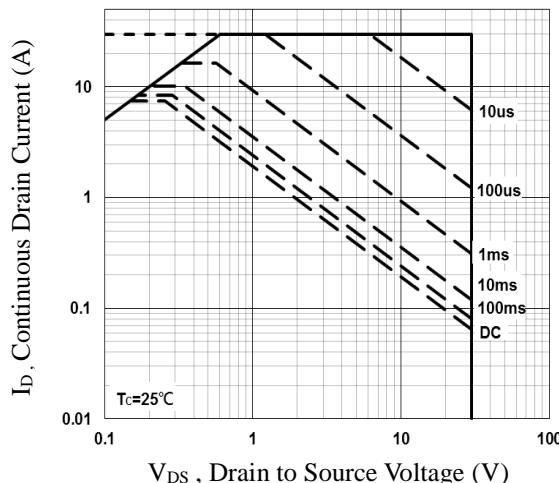
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=5\text{A}$	---	4.1	8	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3, 4</sup>		---	1	2	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3, 4</sup>		---	2.1	4	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{\text{DD}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=6\Omega$	---	2.6	5	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	7.2	14	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>3, 4</sup>		---	15.8	30	
$T_f$	Fall Time <sup>3, 4</sup>		---	4.6	9	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	345	500	pF
$C_{\text{oss}}$	Output Capacitance		---	55	80	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	32	55	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $f=1\text{MHz}$	---	3.2	6.4	$\Omega$

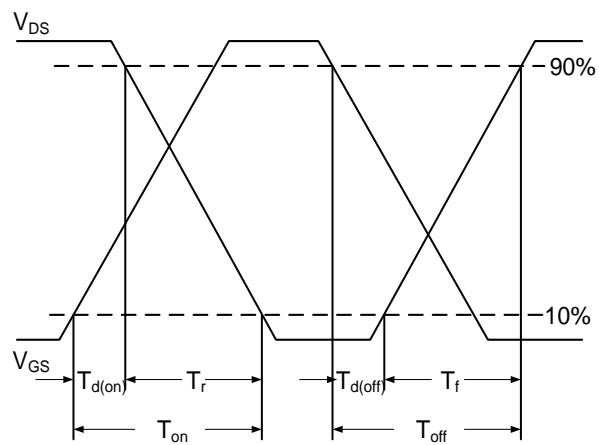
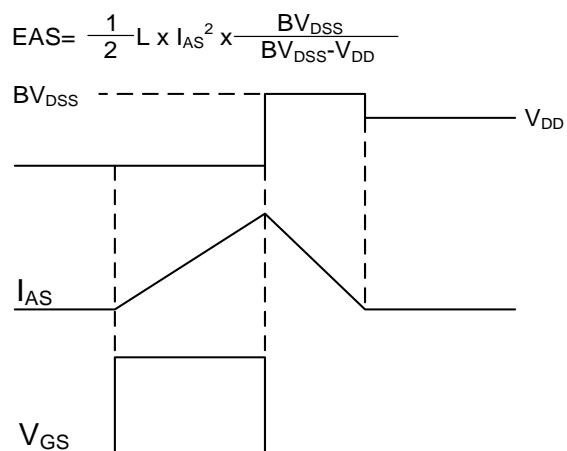
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	7.5	A
$I_{\text{SM}}$	Pulsed Source Current <sup>3</sup>		---	---	30	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>3</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
$t_{\text{rr}}$	Reverse Recovery Time		---	---	---	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	---	---	nC

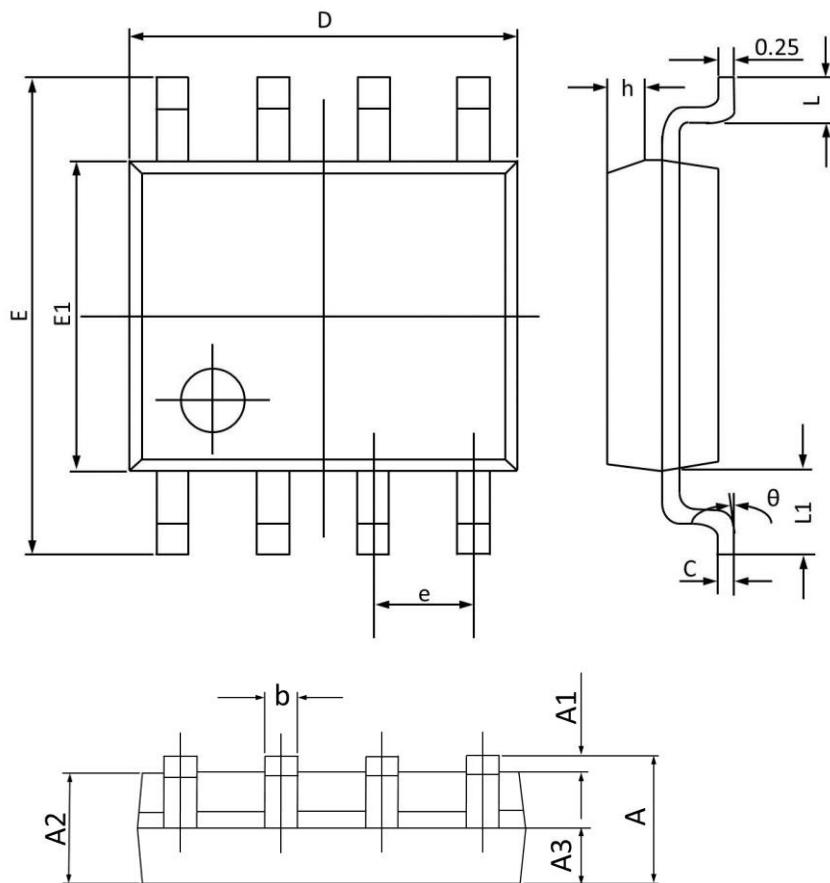
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=17\text{A}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs.  $T_C$** 

**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$** 

**Fig.3 Normalized  $V_{th}$  vs.  $T_J$** 

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Response**

**Fig.6 Maximum Safe Operation Area**


**Fig.7 Switching Time Waveform**

**Fig.8 EAS Waveform**

## SOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.250	1.650	0.049	0.065
A3	0.500	0.700	0.020	0.028
b	0.380	0.510	0.015	0.020
c	0.170	0.260	0.007	0.010
D	4.700	5.100	0.185	0.201
E	5.800	6.200	0.228	0.244
E1	3.700	4.100	0.146	0.161
e	1.270(BSC)		0.050(BSC)	
h	0.250	0.500	0.010	0.020
L	0.400	0.800	0.016	0.031
L1	1.050(BSC)		0.041(BSC)	
θ	0°	8°	0°	8°